APPL NUM 10058650	FILING DATE 01/28/2002	CLASS 209	SUBCLASS £25	GAU 372 9	DH EXAMINER		
**APPLICANTS: Chen Shiuh-Hui; Field Cheryl; Lefebvre Didier; Wang Joe;							
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**CONTINUING DATA VERIFIED:							
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** FOREIGN APPLICATIONS VERIFIED:							
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PG-PUB DO N	OT PUBLISH 🗖		RESCIN	_D 🗀			
Foreign priority claimed							
FITLE: Method of separating and handling a thin semiconductor die on a wafer U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-94)							

NOTICE OF ALLOWANCE MAILED			CLAIMS ALLOWED					
		Assistant Examiner	Total Claims		Print Cla O.G	im for		
ISSUE FEE			DRAWING .					
Amount Due	Date Paid		Sheets Drwg.	Figs.Drv	rg. Pr	int Fig.		
		Primary Examiner						
TERMINAL.		PREPARED FOR ISSUE	Application Examiner					
	DISCLAMER	WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.						
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